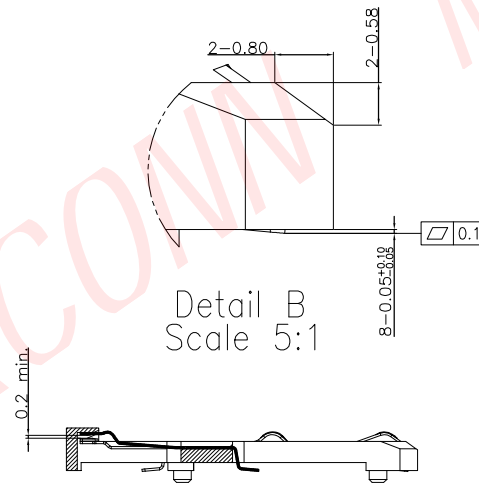
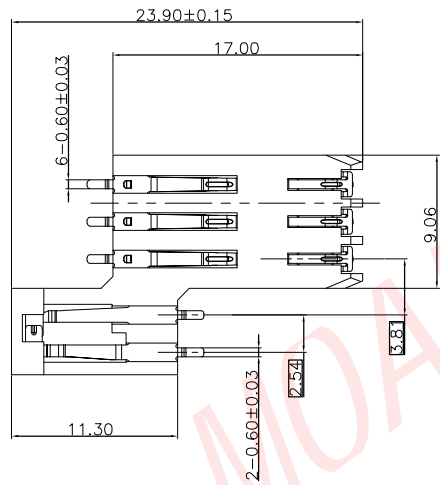
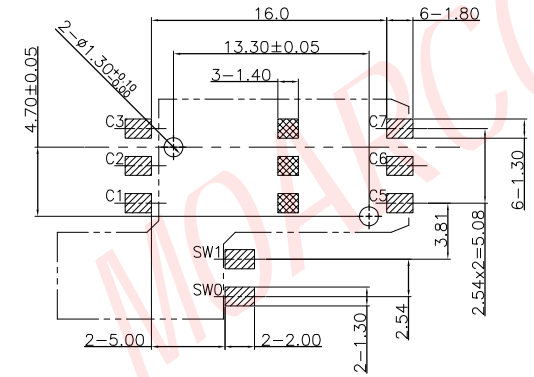


All materials, plating and process meet HF requirements.

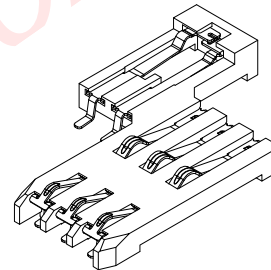
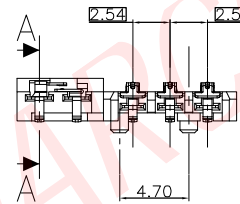
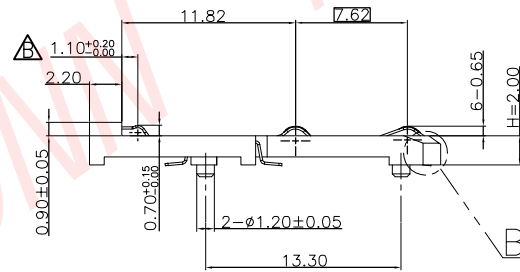


Section A-A



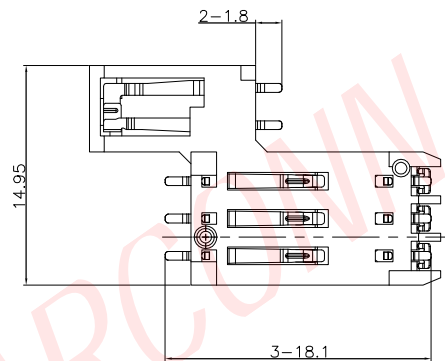
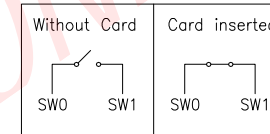
BOARD PAD NO WIRING AREA

Recommended PCB Layout
Gengeral Tolerance : ±0.10mm



NOTE :

- Material:
 - 1-1 Housing: High Temperature Thermoplastic, LCP, Color: Black, UL94V-0
 - 1-2 Terminal and Switch: Phosphor Bronze, T=0.15mm
- Plating:
 - Contact Area: Gold 1μ"
 - Solder Area: Matte Tin 100μ" min.
 - Underplating: Ni overall 80μ" min.
- Specification:
 - 3-1 Contact Current Rating: 0.5A
 - 3-2 Dielectric Withstanding Voltage: AC500V r.m.s.
 - 3-3 Insulation Resistance: 1000 MΩ Minimum, at DC 500V.
 - 3-4 Contact Resistance: 100 mΩ Maximum.
 - 3-5 Mating Cycle: 100,000 Insertions.



MOARCONN
MORE CONNECTIONS SMART FUTURE

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2'

PRODUCT NAME : SMART CARD CONN. H2.00mm	DRAWING: Alexander	DATE: 2019.04.25
PRODUCT NO. : SM200-T1200-01	CHECK:	DATE:
DRAWING NO. : D-SM200-T1200-01	APPROVED:	DATE:
SCALE: 1:1	DWG ID: C D	REV.: A
		PAGE: 1 OF 1

A	----	NEW RELEASE	Alexander	2019.04.25
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE